

January 1997

**NOT RECOMMENDED  
FOR NEW DESIGNS**  
Use CMOS Technology

## Features

- Buffered Inputs
- Typical Propagation Delay: 5.6ns at  $V_{CC} = 5V$ ,  $T_A = 25^\circ C$
- Positive Edge Triggered
- CD74FCT564
  - Inverting
- CD74FCT574
  - Noninverting
- SCR Latchup Resistant BiCMOS Process and Circuit Design
- Speed of Bipolar FAST™/AS/S
- 48mA Output Sink Current
- Output Voltage Swing Limited to 3.7V at  $V_{CC} = 5V$
- Controlled Output Edge Rates
- Input/Output Isolation to  $V_{CC}$
- BiCMOS Technology with Low Quiescent Power

## Description

The CD74FCT564 and CD74FCT574 are octal D-Type, three-state, positive edge triggered flip-flops which use a small geometry BiCMOS technology. The output stage is a combination of bipolar and CMOS transistors that limits the output HIGH level to two diode drops below  $V_{CC}$ . This resultant lowering of output swing (0V to 3.7V) reduces power bus ringing (a source of EMI) and minimizes  $V_{CC}$  bounce and ground bounce and their effects during simultaneous output switching. The output configuration also enhances switching speed and is capable of sinking 48 milliamperes.

The eight flip-flops enter data into their registers on the LOW to HIGH transition of the clock (CP). The Output Enable ( $\overline{OE}$ ) controls the three state outputs and is independent of the register operation. When the Output Enable ( $\overline{OE}$ ) is HIGH, the outputs are in the high impedance state. The CD74FCT564 and CD74FCT574 share the same configurations; the CD74FCT564, however, has inverted outputs and the CD74FCT574 has noninverted outputs.

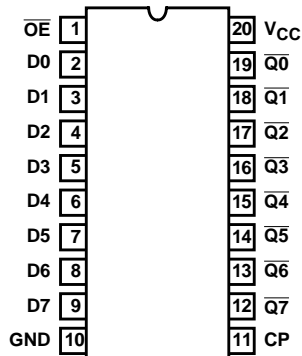
## Ordering Information

PART NUMBER	TEMP. RANGE ( $^\circ C$ )	PACKAGE	PKG. NO.
CD74FCT564E	0 to 70	20 Ld PDIP	E20.3
CD74FCT574E	0 to 70	20 Ld PDIP	E20.3
CD74FCT564M	0 to 70	20 Ld SOIC	M20.3
CD74FCT574M	0 to 70	20 Ld SOIC	M20.3
CD74FCT574SM	0 to 70	20 Ld SSOP	M20.209

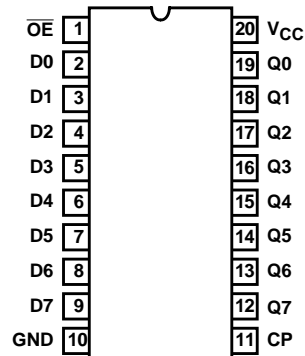
NOTE: When ordering the suffix M and SM packages, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.

## Pinouts

**CD74FCT564**  
(PDIP, SOIC, SSOP)  
TOP VIEW

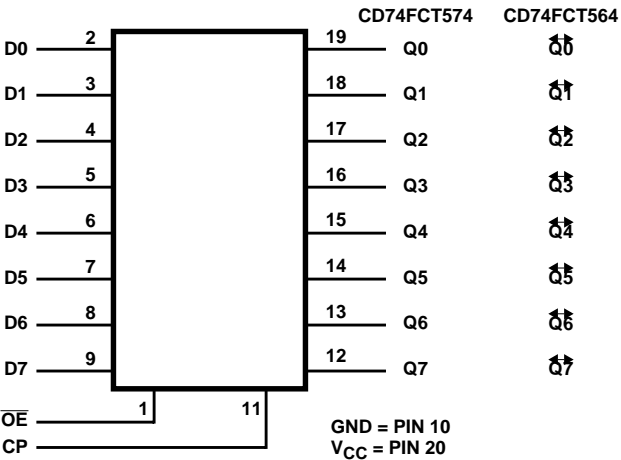


**CD74FCT574**  
(PDIP, SOIC, SSOP)  
TOP VIEW



CD74FCT564, CD74FCT574

Functional Diagram



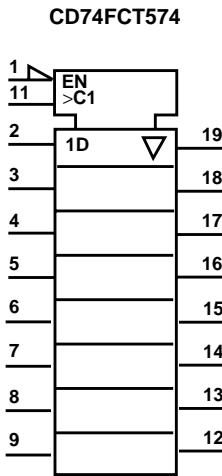
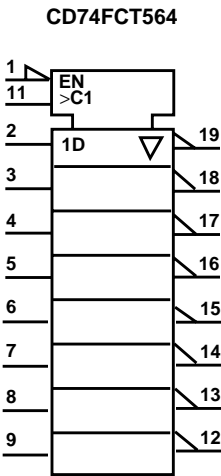
TRUTH TABLE (NOTE 1)

INPUTS			OUTPUTS	
			CD74FCT564	CD74FCT574
OE	CP	DN	QN	QN
L	↑	H	L	H
L	↑	L	H	L
L	L	X	Qo	Qo
H	X	X	Z	Z

NOTE:

- 1. H = High Level (Steady State)  
L = Low Level (Steady State)  
X = Don't Care  
↑ = Transition from low to high level  
Qo = The level of Q before the indicated steady state input conditions were established.  
Z = HIGH Impedance

IEC Logic Symbols



# CD74FCT564, CD74FCT574

## Absolute Maximum Ratings

DC Supply Voltage ( $V_{CC}$ )	-0.5V to 6V
DC Diode Current, $I_{IK}$ (For $V_I < -0.5V$ )	-20mA
DC Output Diode Current, $I_{OK}$ (for $V_O < -0.5V$ )	-50mA
DC Output Sink Current per Output Pin, $I_O$	70mA
DC Output Source Current per Output Pin, $I_O$	-30mA
DC $V_{CC}$ Current ( $I_{CC}$ )	140mA
DC Ground Current ( $I_{GND}$ )	400mA

## Thermal Information

Thermal Resistance (Typical, Note 2)	$\theta_{JA}$ ( $^{\circ}C/W$ )
PDIP Package	135
SOIC Package	125
SSOP Package	130
Maximum Junction Temperature	150 $^{\circ}C$
Maximum Storage Temperature Range	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s)	300 $^{\circ}C$ (SOIC and SSOP-Lead Tips Only)

## Operating Conditions

Operating Temperature Range, $T_A$	0 $^{\circ}C$ to 70 $^{\circ}C$
Supply Voltage Range, $V_{CC}$	4.75V to 5.25V
DC Input Voltage, $V_I$	0 to $V_{CC}$
DC Output Voltage, $V_O$	0 to $\leq V_{CC}$
Input Rise and Fall Slew Rate, $dt/dv$	0 to 10ns/V

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

## Electrical Specifications Temperature Range 0 $^{\circ}C$ to 70 $^{\circ}C$ , $V_{CC}$ Max = 5.25V, $V_{CC}$ Min = 4.75V

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> )				UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		25°C		0°C TO 70°C		
					MIN	MAX	MIN	MAX	
High Level Input Voltage	V <sub>IH</sub>			4.5 to 5.5	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>			4.5 to 5.5	-	0.8	-	0.8	V
High Level Output Voltage	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-15	Min	2.4	-	2.4	-	V
Low Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	48	Min	-	0.55	-	0.55	V
High Level Input Current	I <sub>IH</sub>	V <sub>CC</sub>		Max	-	0.1	-	1	μA
Low Level Input Current	I <sub>IL</sub>	GND		Max	-	-0.1	-	-1	μA
Three-State Leakage Current	I <sub>OZH</sub>	V <sub>CC</sub>		Max	-	0.5	-	10	μA
	I <sub>OZL</sub>	GND		Max	-	-0.5	-	-10	μA
Input Clamp Voltage	V <sub>IK</sub>	V <sub>CC</sub> or GND	-18	Min	-	-1.2	-	-1.2	V
Short Circuit Output Current (Note 3)	I <sub>OS</sub>	V <sub>CC</sub> = 0 V <sub>CC</sub> or GND		Max	-60	-	-60	-	mA
Quiescent Supply Current, MSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	Max	-	8	-	80	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High, 1 Unit Load	ΔI <sub>CC</sub>	3.4V (Note 4)		MAX	-	1.6	-	1.6	mA

NOTES:

- Not more than one output should be shorted at one time. Test duration should not exceed 100ms.
- Inputs that are not measured are at  $V_{CC}$  or GND.
- FCT Input Loading: All inputs are 1 unit load. Unit load is  $\Delta I_{CC}$  limit specified in Static Characteristics Chart, e.g., 1.6mA Max at 70 $^{\circ}C$ .

# CD74FCT564, CD74FCT574

## Switching Specifications Over Operating Range $t_r, t_f = 2.5\text{ns}$ , $C_L = 50\text{pF}$ , $R_L$ - See Figure 4

PARAMETER	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> )			UNITS
			25°C	0°C TO 70°C		
			TYP	MIN	MAX	
Propagation Delays						
Clock to Q CD74FCT574	t <sub>PLH</sub> , t <sub>PHL</sub>	5	6.6	2	10	ns
Clock to Q̄ CD74FCT564	t <sub>PLH</sub> , t <sub>PHL</sub>	5	6.6	1.5	10	ns
Output Disable to Q CD74FCT574	t <sub>PLZ</sub> , t <sub>PHZ</sub>	5	6	1.5	8	ns
Output Enable to Q CD74FCT574	t <sub>PZL</sub> , t <sub>PZH</sub>	5	9	1.5	12.5	ns
Output Disable to Q̄ CD74FCT564	t <sub>PLZ</sub> , t <sub>PHZ</sub>	5	6	1.5	8	ns
Output Enable to Q̄ CD74FCT564	t <sub>PZL</sub> , t <sub>PZH</sub>	5	9	1.5	12.5	ns
Power Dissipation Capacitance	C <sub>PD</sub> (Note 6)	-	34 Typical			pF
Minimum (Valley) V <sub>OHV</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OHV</sub> (Figure 1)	5	0.5	-	-	V
Maximum (Peak) V <sub>OLP</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OLP</sub> (Figure 1)	5	1	-	-	V
Input Capacitance	C <sub>I</sub>	-	-	-	10	pF
Three State Output Capacitance	C <sub>O</sub>	-	-	-	15	pF

### NOTE:

- $C_{PD}$ , measured per flip-flop, is used to determine the dynamic power consumption.  
 $PD$  (per package) =  $V_{CC} I_{CC} + \Sigma(V_{CC}^2 f_I C_{PD} + V_O^2 \text{ to } C_L + V_{CC} \Delta I_{CC} D)$  where:  
 $V_{CC}$  = supply voltage  
 $\Delta I_{CC}$  = flow through current x unit load  
 $C_L$  = output load capacitance  
 $D$  = duty cycle of input high  
 $f_O$  = output frequency  
 $f_I$  = input frequency

## Prerequisite For Switching

PARAMETER	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> )			UNITS
			25°C	0°C TO 70°C		
			TYP	MIN	MAX	
Clock Pulse Width CD74FCT574	t <sub>W</sub>	5 (Note 7)		7	-	ns
CD74FCT564	t <sub>W</sub>	5		7	-	ns
Setup Time Data to Clock	t <sub>SU</sub>	5		2	-	ns
Data to Clock Hold Time						
CD74FCT574	t <sub>H</sub>	5		2	-	ns
CD74FCT564	t <sub>H</sub>	5		2	-	ns
Maximum Clock Frequency	f <sub>MAX</sub>	5		70	-	MHz

### NOTE:

- 5V: minimum is at 4.5V.  
5V: minimum is at 4.75V for 0°C to 70°C.  
Typical is at 5V.

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